

On page 11, line 16, after "layer" please delete "24" and insert --26--;

On page 11, line 23, after "A" please delete "course" and insert --coarse--;

On page 12, line 3, after "further" please delete "provides" and insert --provide--;

On page 12, line 24, after "28" please insert --and polyimide layer 26--.

### IN THE CLAIMS

Please amend the claims as follows:

1 1. (Amended) A method for manufacturing a plurality of thinned integrated  
2 circuits from a semiconductor wafer having a thickness, a front surface and a backside  
3 surface, comprising:  
4 defining a plurality of grooves into said front surface of said semiconductor wafer  
5 to define said plurality of dies, said grooves penetrating into said surface at a  
6 predetermined distance less than said thickness of said semiconductor wafer so that  
7 said plurality of dies remain integral with said wafer;  
8 mounting said wafer to a flat rigid substrate to support said wafer, said wafer  
9 being mounted to said substrate with said front surface turned toward said substrate;  
10 mechanically removing a predetermined portion of said backside of said wafer  
11 until said thickness of said wafer is reduced to expose said plurality of grooves to said  
12 backside in preparation to separating said plurality of said dies, said dies remaining [of]  
13 mounted to said substrate; and  
14 releasing said plurality of dies from said substrate.